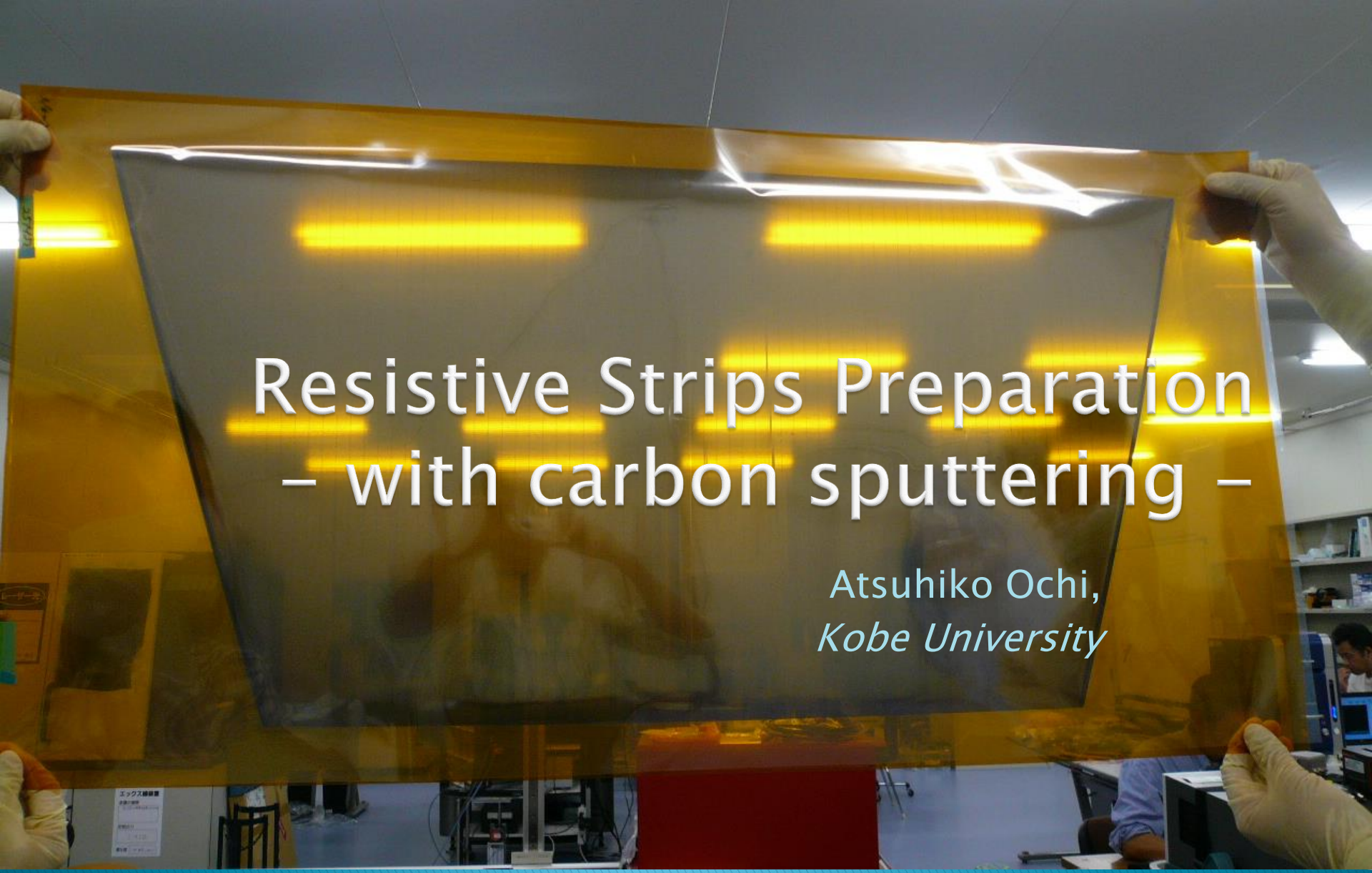


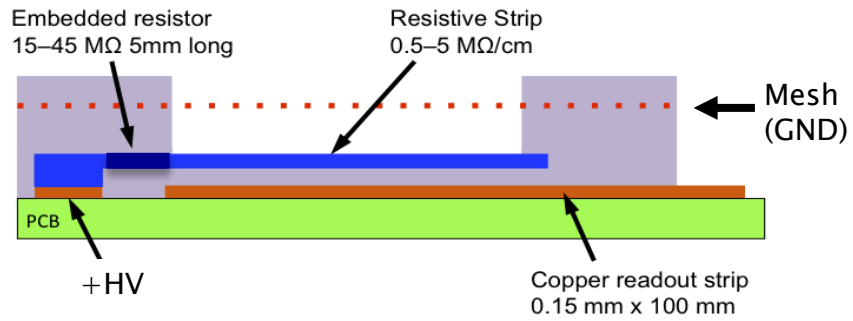
Resistive Strips Preparation – with carbon sputtering –

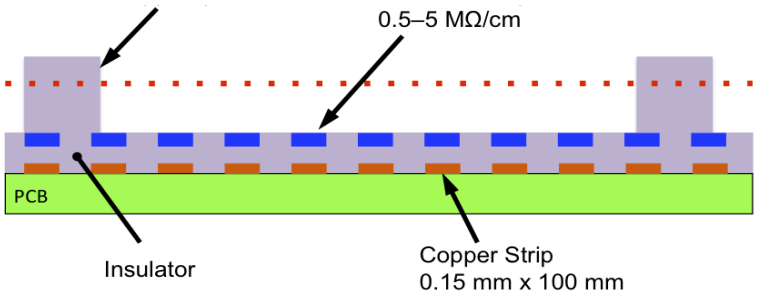
Atsuhiko Ochi,
Kobe University

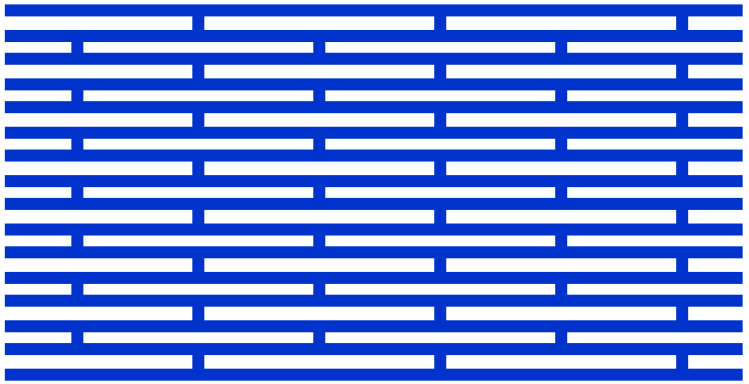
05/11/2013 MM General meeting@ CERN

Requirements for ATLAS NSW MM

- High position resolution for one dimension
  - <100 μm for eta direction. (Resolution of a few cm is allowed for second coordinate.)
- Tolerant for high rate HIP particles
  - ~ 5kHz/cm^2
- Resistive layer should be formed as strips
- Resistivity: ~20MΩ/cm
  - To protect from spark
- Mass production should be available, with large size (1m)
  - ~2000 board should be produced in half year.
- Low cost





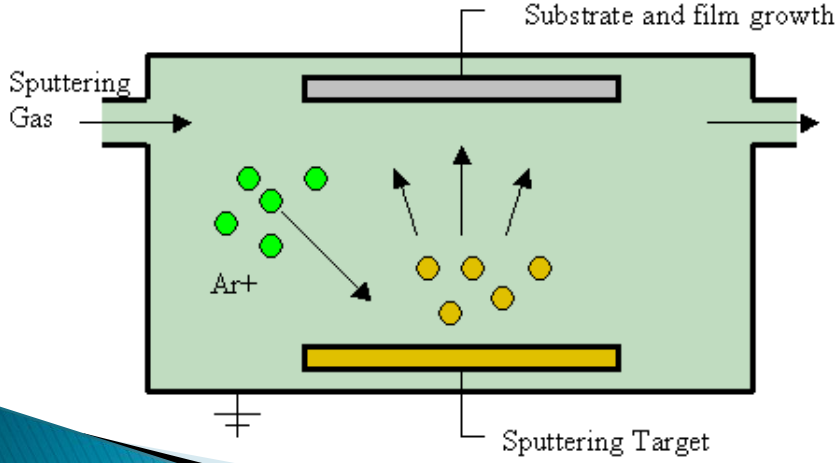


Two option for resistive electrodes

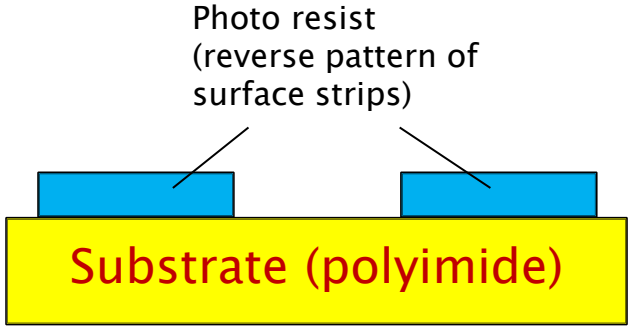
- Screen printing
  - Already several prototypes (@ CERN and Japan) has been produced.
  - Made from carbon loaded polymer.
  - Large size (>1m^2) is available
  - 400 μm pitch was available for MAMMA production.
- Sputtering with lift off process
  - New technique.
    - Just first two prototypes (10cm x 10cm MM) are available at June.
  - Fine pattern (~10μm) is available.
  - Large size (>1m^2) is available in industrial facilities.
  - Production quality is very well.
    - It is not affected by production environment

Liftoff process using sputtering

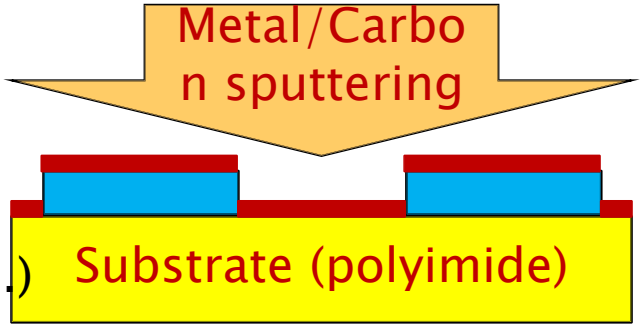
- Very fine structure (a few tens micro meter) can be formed using photo resist. (same as PCB)
- Surface resistivity can be controlled by sputtering material and their thickness



@PCB company (Laytech inc.)



@Sputtering company (Be-Sputter inc.)

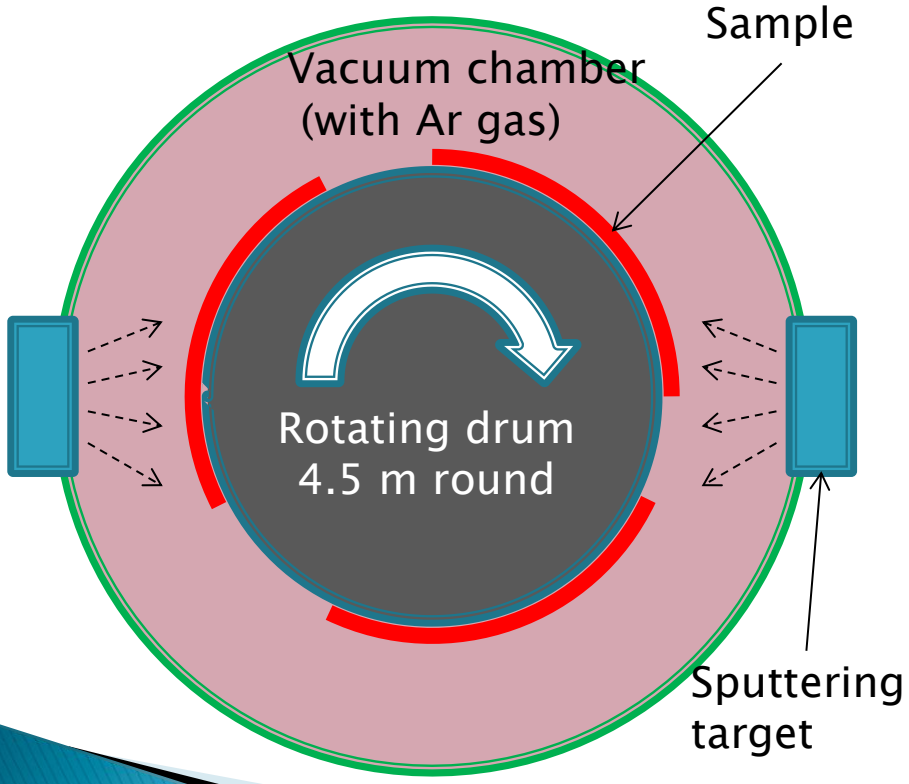


Developing the resists

@PCB company (Laytech inc.)

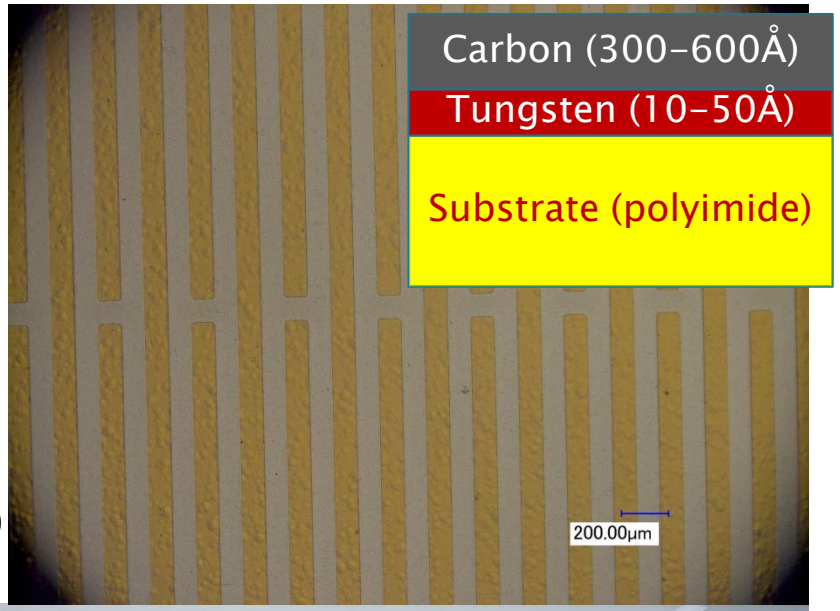
Sputtering facilities

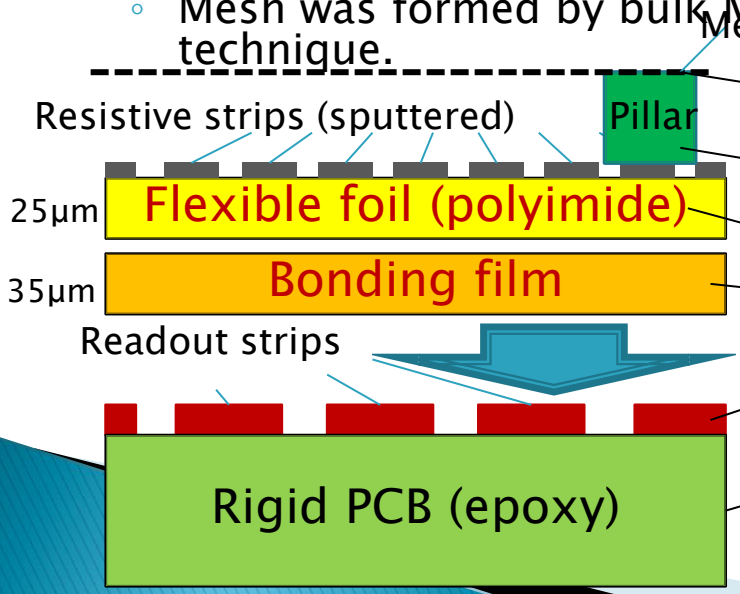
- Large size sputtering is available
  - 4.5m x 1m for flexible film

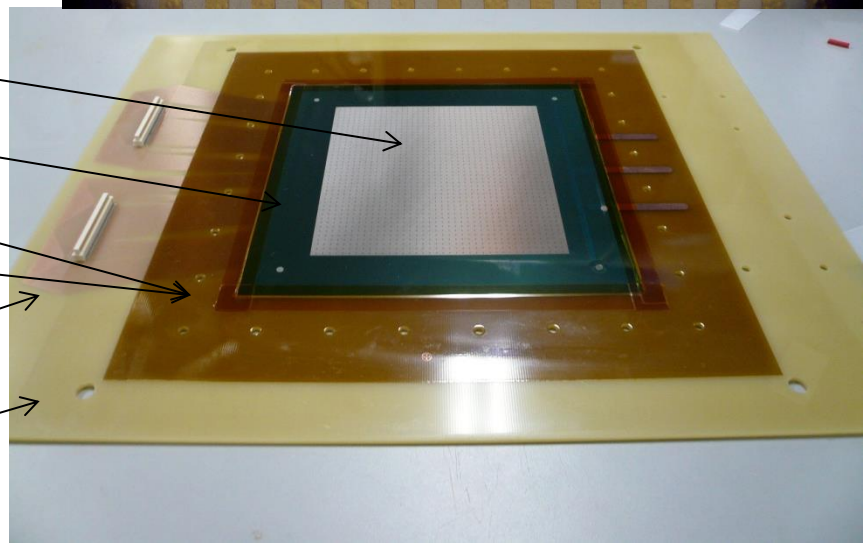


Prototype of small MicroMEGAS

- June, 2013
- The readout board consists of
  - Readout strips (Rigid PCB).
  - Resistive strip foil (Polyimide film).
  - Fine strip pitch of 200 μm is formed on 25μm polyimide foil.
  - More fine structure will be available.
  - Surface resistivity: 1M/sq.
    - With 300Å carbon+50Å tungsten
  - Substrate thickness : 60 μm. (25μm polyimide & 35μm bonding film)
  - Mesh was formed by bulk MM technique.

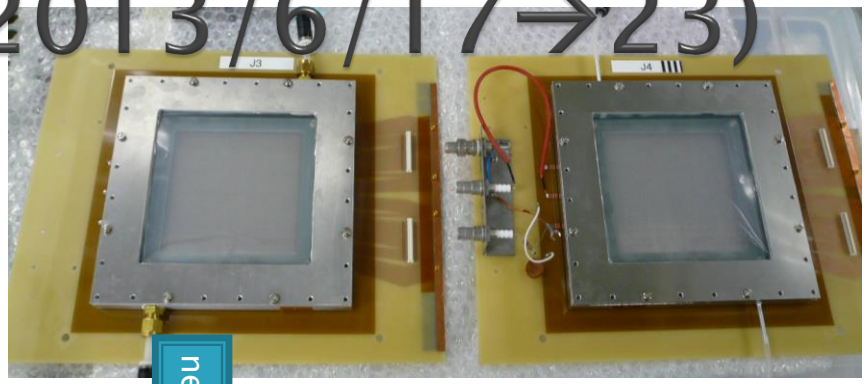


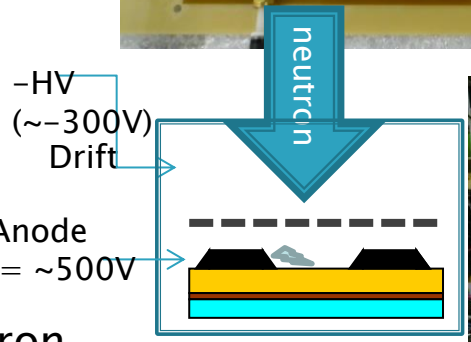


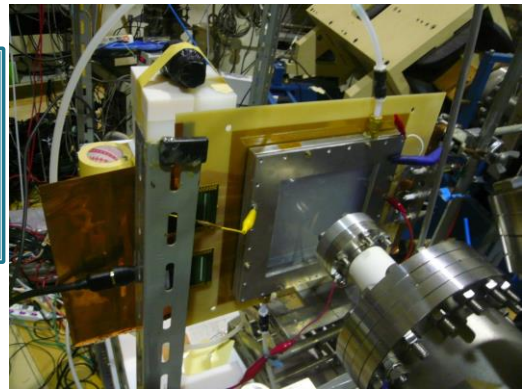


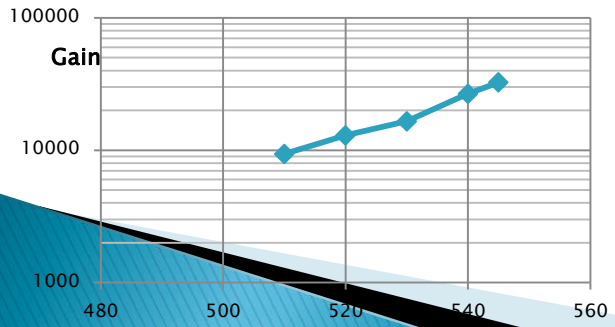
Fast neutron test (2013/6/17→23)

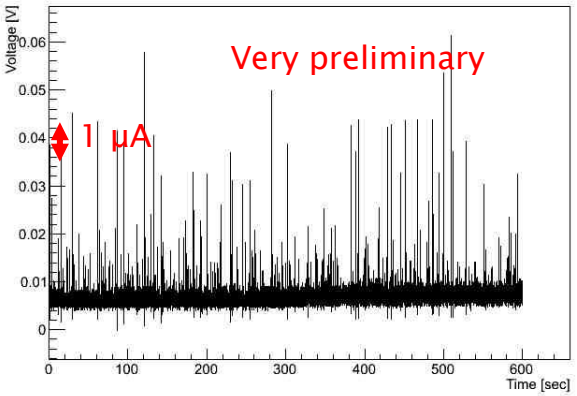
- The first beamtest for sputtering MPGD
- Gain curve of 5.9 keV X-ray.
  - Drift = -300V
  - Drift spacing: 5mm
  - Gas: Ar(93%) + CO2(7%)
- Fast Neutron test
  - Spark probability
  - @Kobe Univ.
    - 17-23 Jun. 2013
  - HV current log under intense neutron.
    - Neutron intense : ~ 10^5 cps/cm^2.
    - 0.01V correspond to 1 μA
    - ~600nA of base current was found while beam ON.





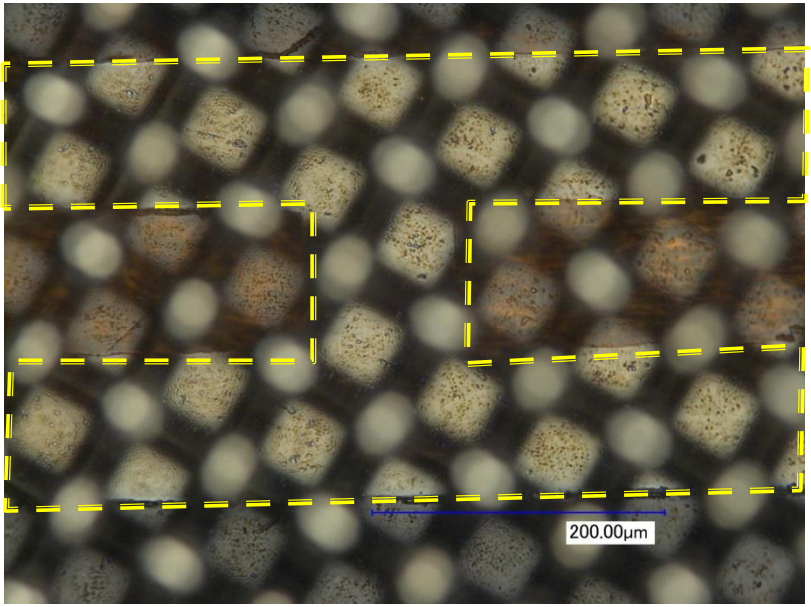


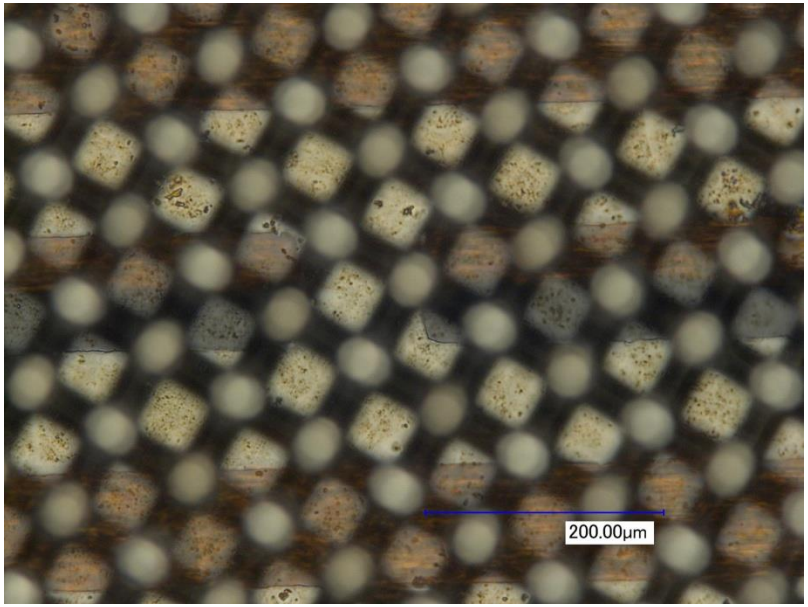




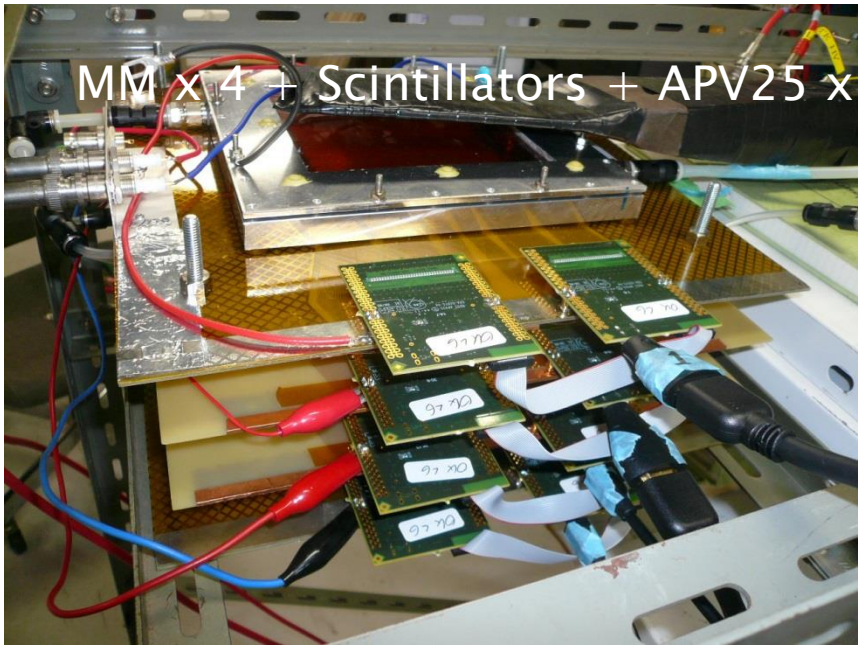
Before and after test

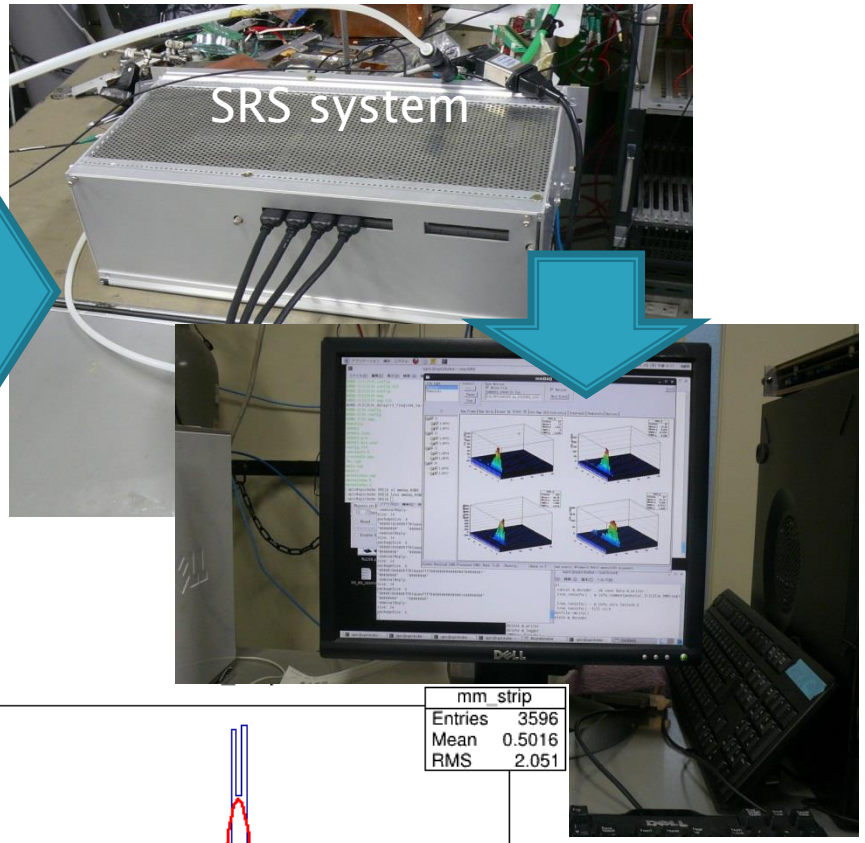
- No destruction is observed on the resistive strips between before and after neutron test



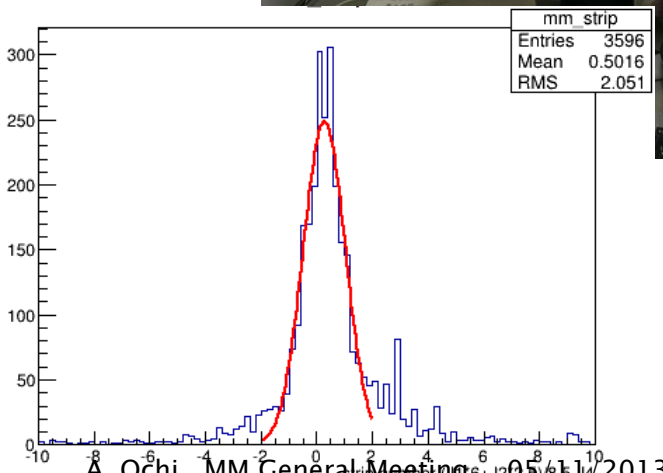


Cosmic test using 4 chambers





- Cosmic test bench using 4 MMs
  - Now taking data
  - More tune needed …
- 2GeV electron beamtest is planed from 18th November
  - At Spring-8 BL33 beamline

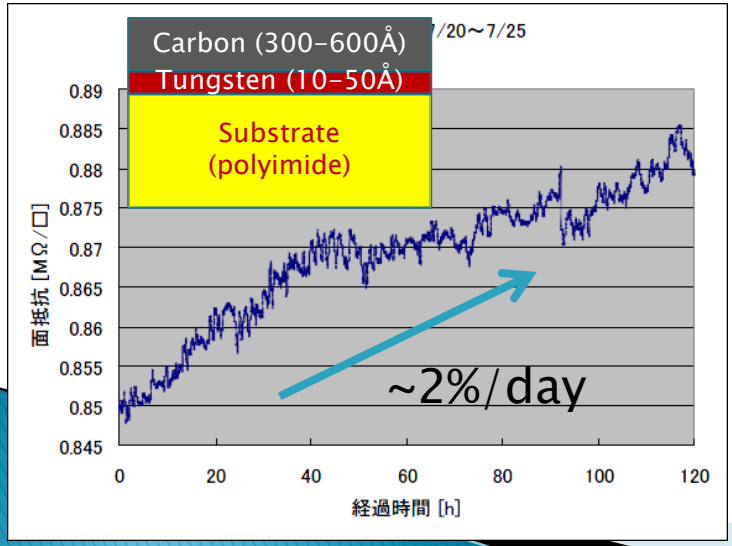


Further improvements and tests for carbon sputtering

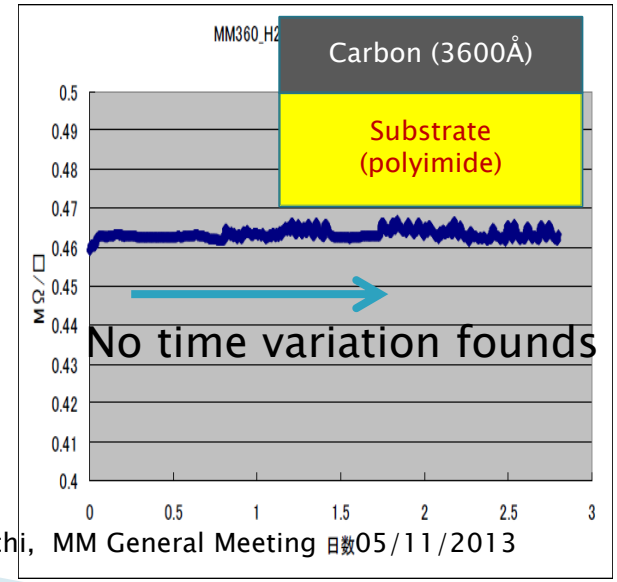
- Requirements for carbon strips
  - Resistive control
    - 20 MΩ/cm is required
      - It correspond to 600kΩ/sq. (our first prototype has 10MΩ /sq.)
      - Thicker carbon sputter is required
    - Long time stability of resistivity
      - The resistivity of early prototypes were growing up as time goes on (~2%/day)
      - It was thought that the oxidation of metal (tungsten layer)
      - Is the carbon sputtering without metal layer possible?
  - Mechanical / chemical robustness test
    - Peeling off property (cross cut method)
    - Resistive stability against the bending of the foil
    - Chemical stabilities
      - For alkali and acid, used for PCB process.

Thick carbon (only) sputtering

- Early prototype:
  - Tungsten (10-50Å) +Carbon (300-600Å)
  - Lower resistivity (<1MΩ/sq.) was available using thickness control of the metal.
  - Time variation founds (~2%/day) after several weeks from sputtering

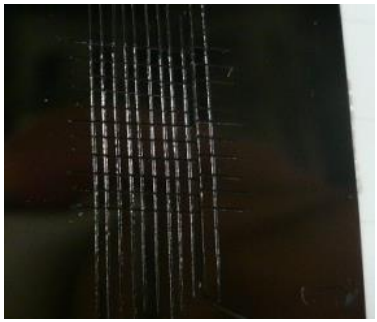


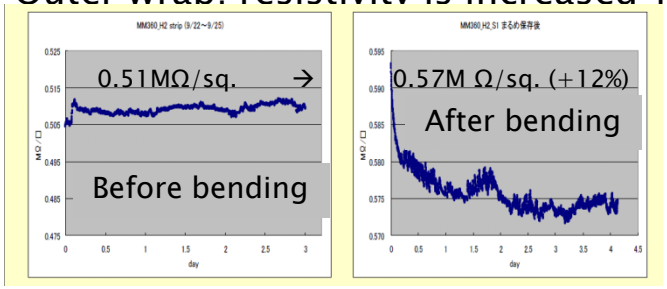
- New prototype: (delivered at September)
  - Carbon only, 3600Å
  - Surface resistivity ~ 500kΩ/sq.
  - No time variation founds after several days from sputtering



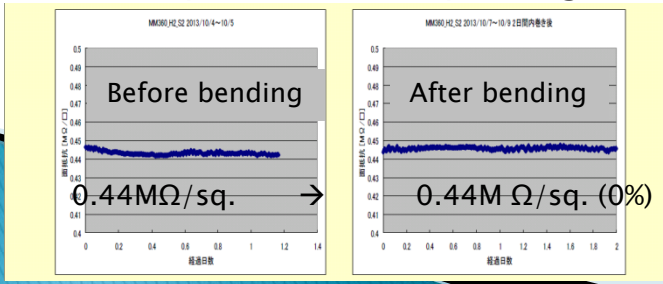
Mechanical robustness for new sputtering carbon

- Adhesion test
  - Cross-cut test (JIS k5400-8.5 standard, similar to the ISO 2409)
  - No peeled carbon founded
- Bending test
  - Bending diameter > 4cm → No resistivity change found
  - Jackknife bending → Conductivity is lost
  - Bending diameter = 1.2cm → Outer wrap: resistivity is increased 10-20%



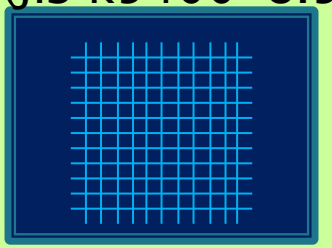


→ Inner wrap: no resistivity change

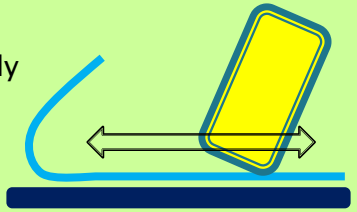


Cross-cut test (JIS k5400-8.5)

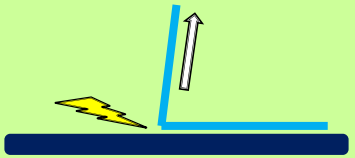
Making cut lines as grid (11 x 11, 1mm pitch)



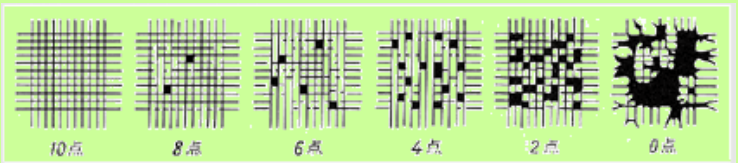
Tape up the foils strongly



Peel off the tape at once



Observe the tape and foils.

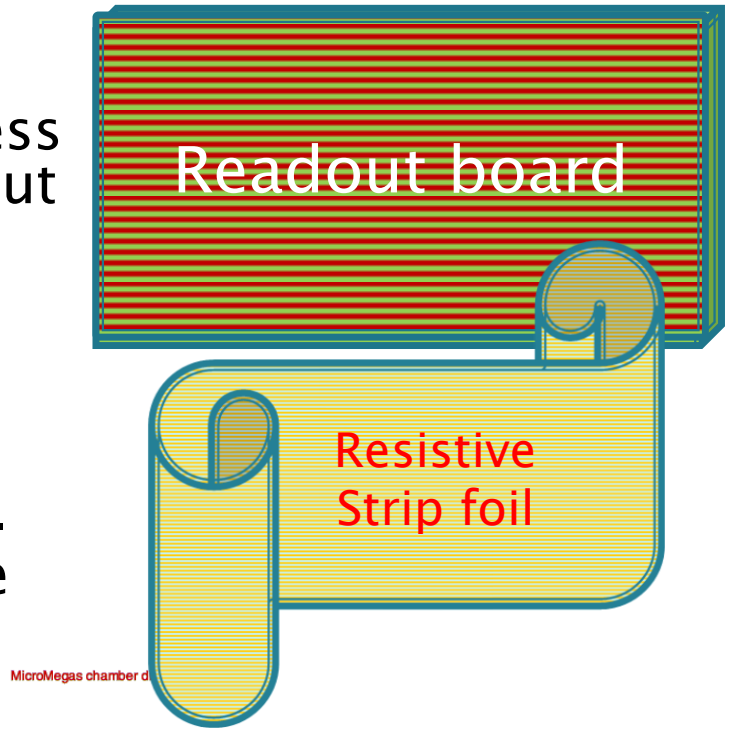


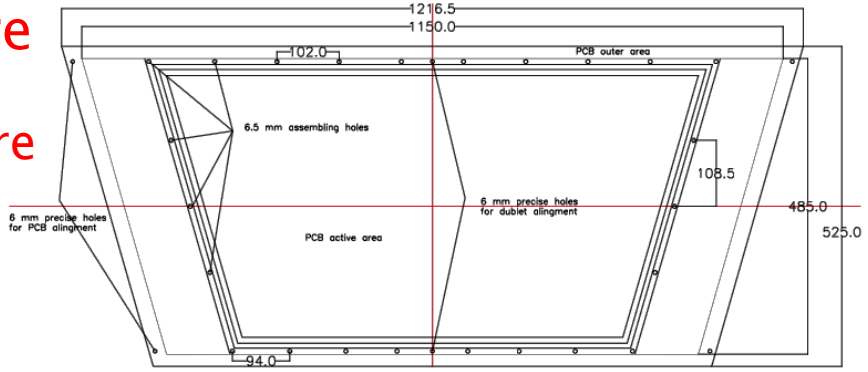
Chemical robustness for new sputtering carbon

- Acid and alkali for PCB processing
  - Hydrochloric acid
  - Nitric acid
  - Sulfuric acid
  - Sodium carbonate
    → No damage on sputtered carbon
  - Sodium hydroxide
    → No damage for short dip
    → Peeling is found after 90 minutes dipping
- **Almost all process of PCB production will not affect to the sputtering carbon**

Prototype of large MMs

- We can divide the production process of resistive strip from that of readout board.
  - Resistive strip is formed on thin foil
  - We don't need fine alignment between resistive strips and readout strips.
- Dividing those processes will make the yield of production growing up.
- We are preparing the large resistive strip foil.
  - Size of foils: 500mm x 1000mm
  - 4 foils are need for a quadruplet
- 8 Foils (4 foils and 4 spare) were delivered to us at 25th October.
  - Some basic resistive parameters are checked.
  - I brought them to CERN today.





For patterning process

RAYTECH

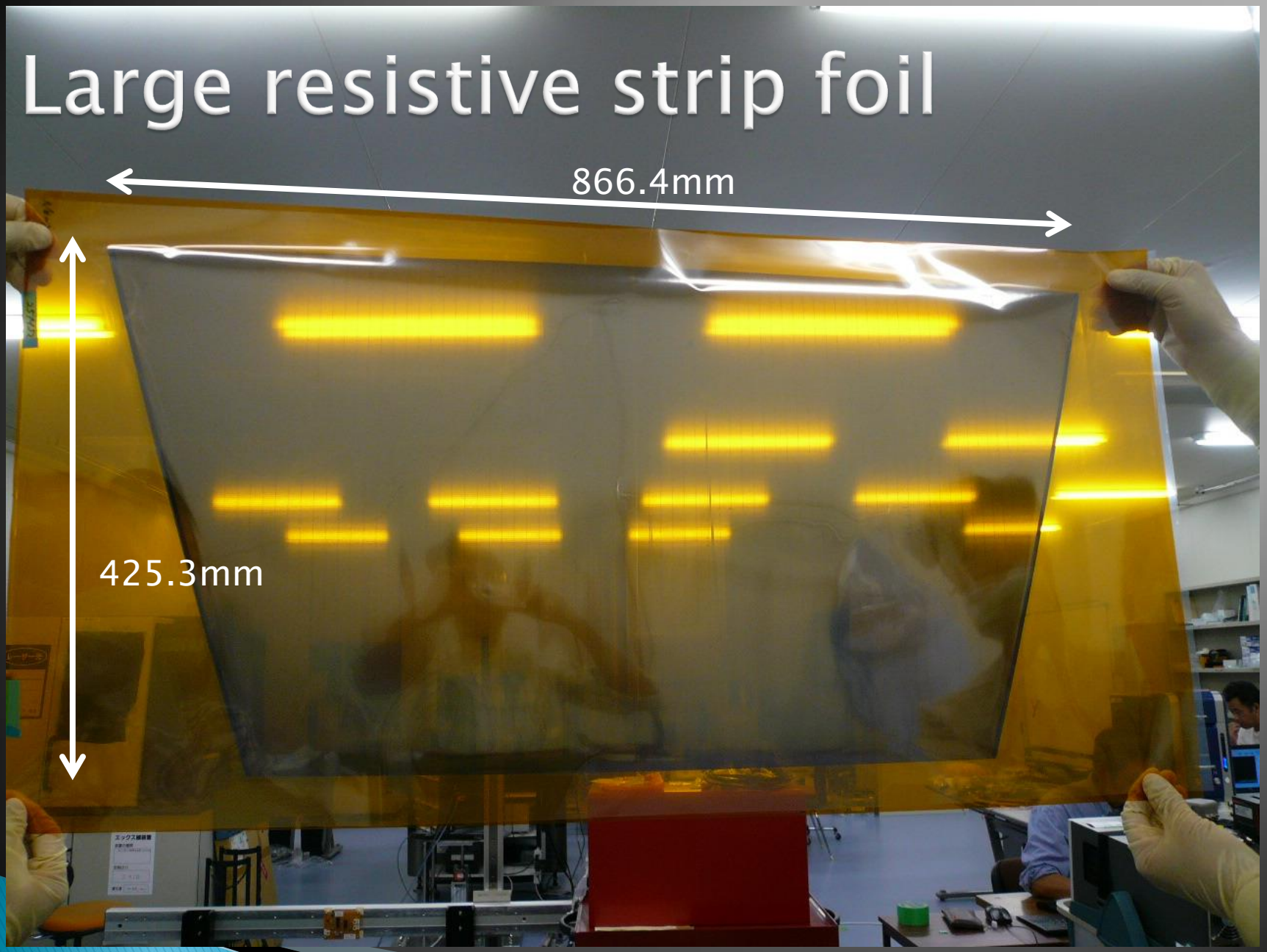
- PCB company
  - They are expert for FPC (Flexible Printed Circuit) production.
  - Liftoff is basic process for FPC production

Exposure machines in clean room

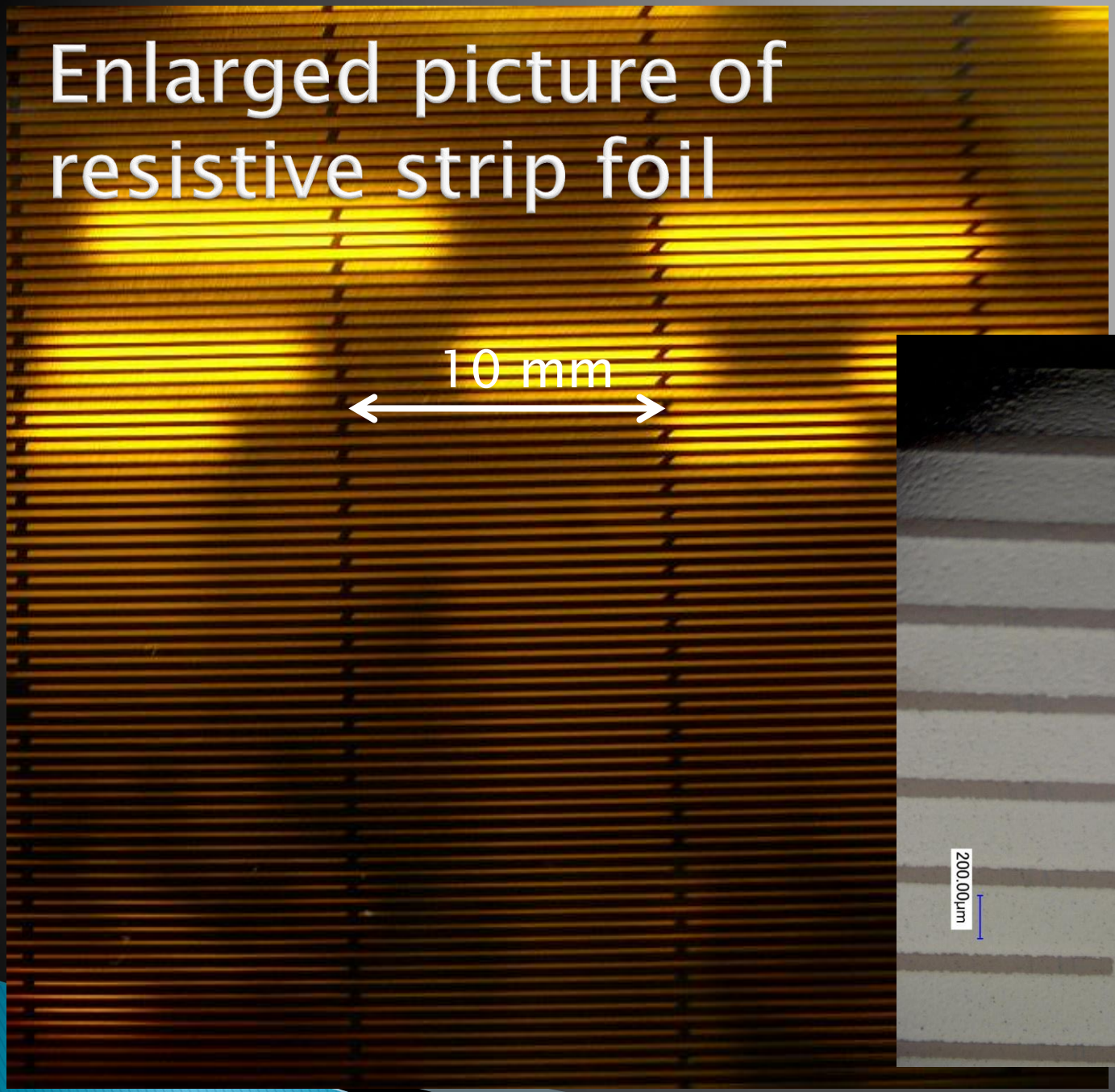
Electro forming machines

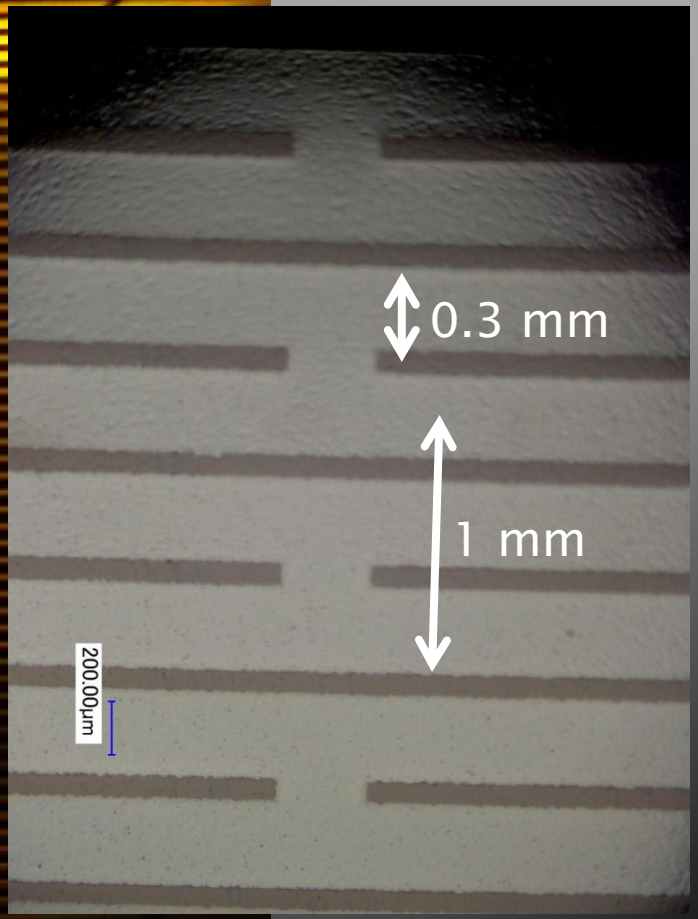
Etching machines

Large resistive strip foil



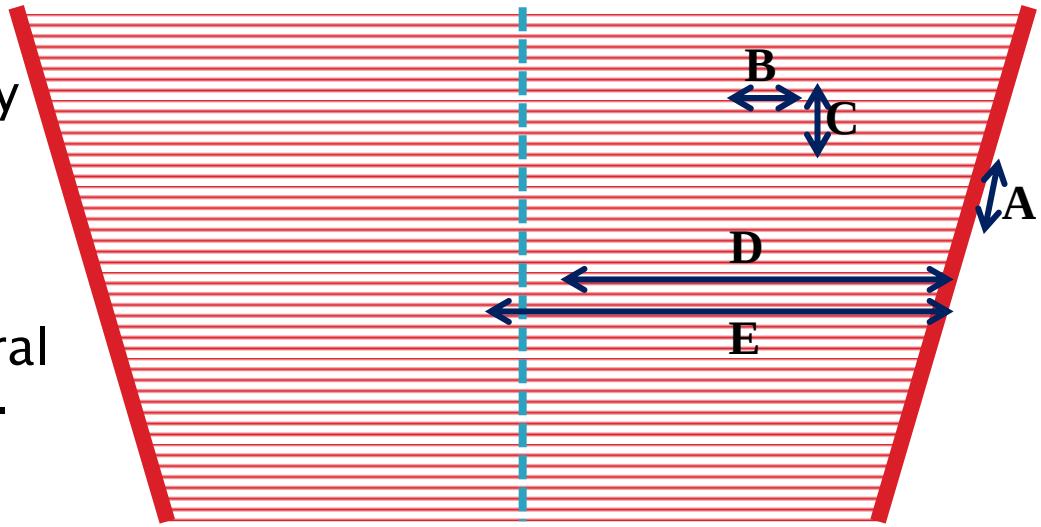
Enlarged picture of resistive strip foil





Resistivity check

- We have no systematic way for resistivity test yet, so these results are based on rough measurements.
- However, we have check surface resistivity on several points for 8 foils as figure.
- The prove has about 2cm width.
- Distance between proves are, A,B,C: 1.5-2.5 cm, D: 30 cm, E: cross over a center line.
- "Inf" means more than 50MΩ.

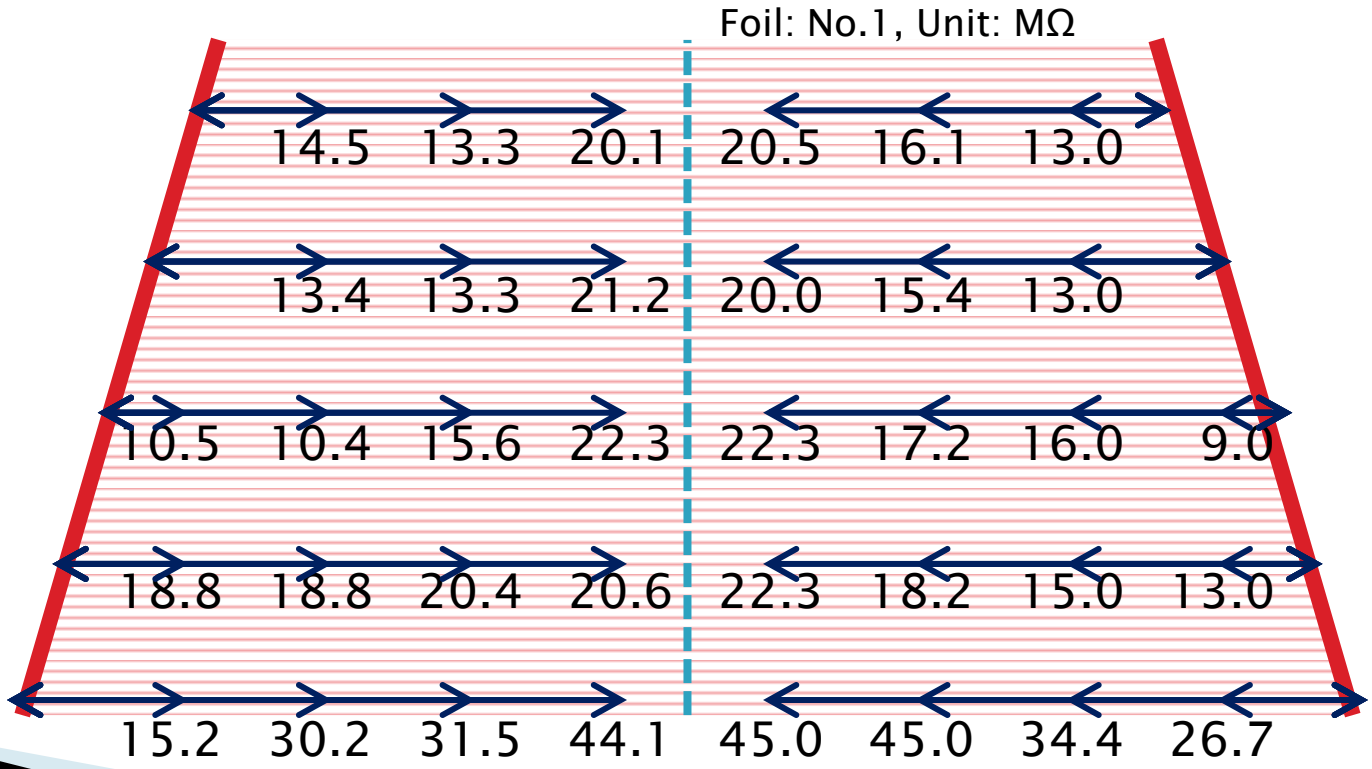


Unit: MΩ

No.	A	B	C	D	E
1	1.4	4	15	6	Inf
2	2.7	2.2	15	9.5	Inf
3	1.5	2.2	13.1	8.3	Inf
4	2.8	1.5	11	6.6	Inf
5	2.2	1.8	10.5	6.3	Inf
6	1.9	2.1	10	6.9	Inf
7	2.5	2.3	10.6	7.4	Inf
8	2.4	2.5	12.3	7.3	Inf

Resistivity check from

- Resistivity from edge to lattice point (10cm x 10cm) were measured.
- Prove shape is point like.



Conclusion

- Prototype of MicroMEGAS using sputtered resistive electrodes were produced and tested.
- It works as same as conventional resistive strip MicroMEGAS
  - Gain curve, operation in HIP were tested. It's OK.
  - We are checking position/timing properties.
- Carbon sputtering process is improved for ATLAS MicroMEGAS
  - Appropriate resistivity ~ 500kΩ/sq.
  - Good mechanical/chemical properties
- Large resistive strip foils are produced for large quadruplet.
  - Qualitative resistivity check is ok.
  - Systematic check for QA is needed.